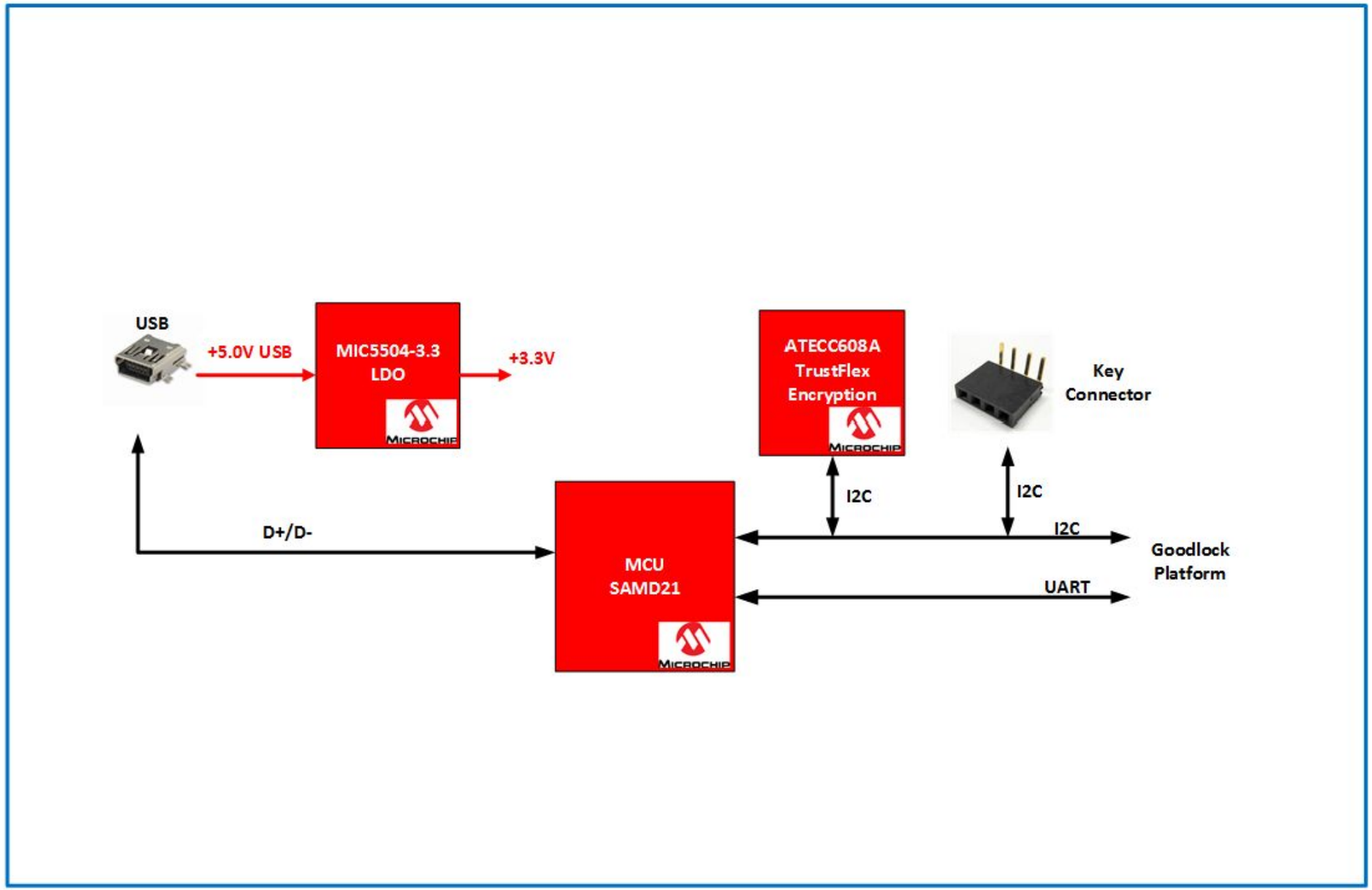
TrustFlexShield Rev 0



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Designed by: M. Bernier	Drawn by: M. Bernier
Checked by: M. Bernier	Approved by: M. Bernier

Future Electronics - System Design Center NA
237 Hymus Blvd.
Pointe-Claire, Quebec, Canada
H9R 5C7

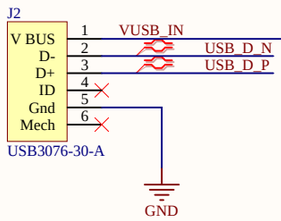
Project Name: TrustFlex_Shield Rev 0

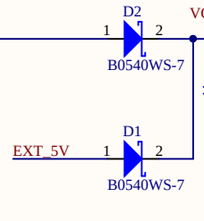
Title: Block Diagram

Size: B | Dwg No.: FEN-524534-SCH-R0 | Rev: 0

Date: 2/24/2020 | Sheet: 1 of 2 | Variant: TrustFlex_Rev0

USB





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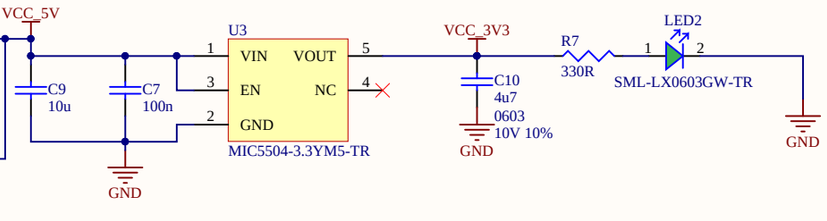

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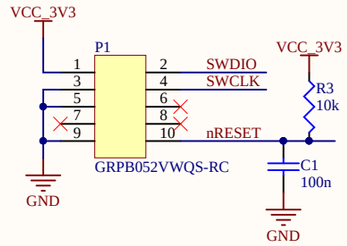

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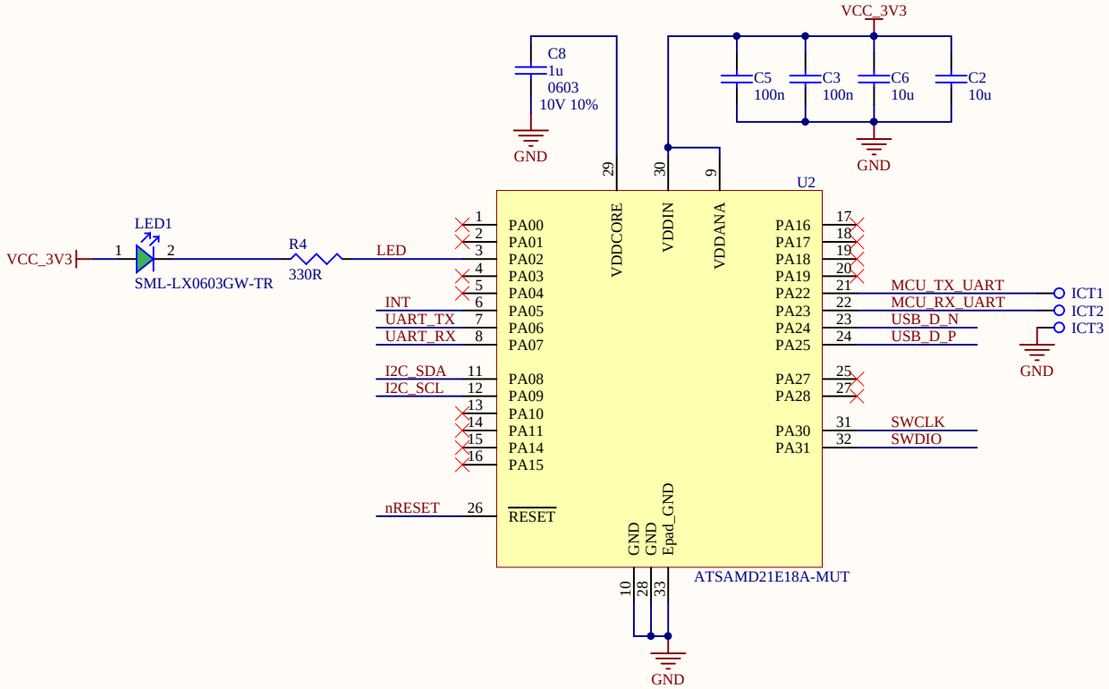

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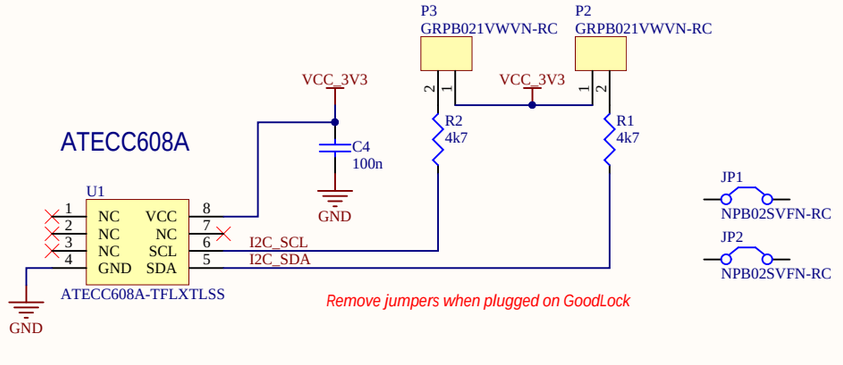

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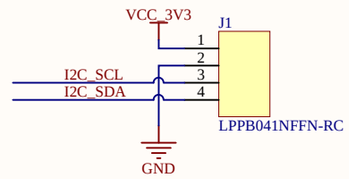
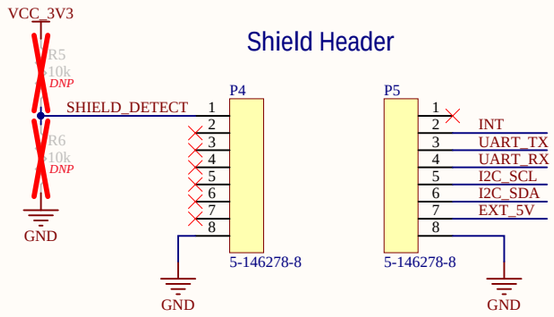


Shield Header



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237 Hymus Blvd.
Pointe-Claire, Quebec, Canada
H9R 5C7

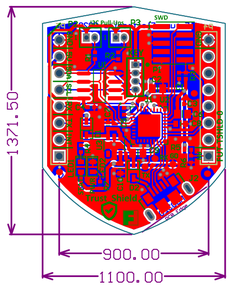
Project Name	TrustFlex_Shield Rev 0
Title	TrustFlex Shield
Designed by	M. Bernier
Drawn by	M. Bernier
Checked by	M. Bernier
Approved by	M. Bernier
Size	B
Dwg No.	FEN-524534-SCH-R0
Rev	0
Date	2/24/2020
Sheet	2 of 2
Variant:	TrustFlex_Rev0

Layers	Top Layer	Bottom Layer

Impedance Requirements

	Impedance 50 Ohms	Impedance 90 Ohms (Diff)		Impedance 100 Ohms (Diff)	
Layer	Trace Width (mils)	Trace Width (mils)	Trace Spacing (mils)	Trace Width (mils)	Trace Spacing (mils)
Top Layer					
Bottom Layer					

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4 HTg	58.00mil	4.3	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARD SPECS - BOARD SHALL BE MANUFACTURED TO MEET ALL SPECS DEFINED UNDER IPC-A-600 (LATEST REVISION)

2. BASE MATERIAL - FR4 High Tg [X] Metal Core [ ] Other [ ] _____
   - Tg for LAMINATE AND PREPREG SHALL BE GREATER THAN OR EQUAL TO 170°C

3. COPPER FOIL WEIGHT - SEE TABLE FOR STACK-UP DETAIL

4. PLATING - 0.5oz [X] 0.75oz [ ] 1oz [ ] Other [ ] _____

5. FINISH - HASL RoHS [X] HASL [ ] Immersion Silver [ ] Immersion Tin [ ] ENIG [ ]
   Other [ ] _____

6. SOLDER MASK - APPLY SOLDER MASK AS PER SPECIFIED IPC-SM-840 ON PCB OVER BARE COPPER
   - GREEN [ ] WHITE [ ] BLUE [ ] Other [X] BLACK

7. SILKSCREEN - LPI - APPLY EPOXY BASED INK
   - TOP/BOTTOM [X] TOP ONLY [ ] BOTTOM ONLY [ ] NONE [ ]
   - WHITE [X] BLACK [ ] Other [ ] _____

8. IMPEDANCE CONTROL - NO [X] YES [ ] SEE TABLE FOR DETAIL

9. ELECTRICAL TEST - 100% IPC-D-356B

10. ALL PLATED AND NON-PLATED THROUGH HOLES ARE TO BE DRILLED AT PRIMARY DRILL STEP
    - ALL HOLES LOCATION TOLERANCES ARE TO BE +/- .002 IN REFERENCE TO THE PRIMARY DATUM

11. GERBER FILES - SUPPLIED GERBER FILES MUST NOT BE MODIFIED WITHOUT PRIOR PERMISSION FROM THE CLIENT

12. LOGO - ONLY LOGOS SUPPLIED IN GERBER FILES WILL BE ACCEPTED ON PCB

13. TOOLING HOLES - NO HOLES SHALL BE PERMITTED WITHIN THE BOARD AREA, EXCEPT THOSE INDICATED IN THE DRILL LEGEND

14. REGISTRATION - REGISTRATION OF PATTERNS TO BE WITHIN +/- .005 LOCATION OF PATTERN ON BOARD TO DIMENSION SHOWN

☑

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Pointe-Claire, Quebec, Canada
H9R 5C7

Designed by: M. Bernier	Drawn by: M. Bernier	Project #	TrustFlex_Shield_RevO
Checked by: M. Bernier	Approved by: M. Bernier	Title:	TrustFlex Shield board
		Size: B	DWG NO: FEN-524534-PCB-RO REV: O
		Date: 2/24/2020	Sheet 1 of 1

Layers	Top Layer	

Impedance Requirements

	Impedance 50 Ohms	Impedance 90 Ohms (Diff)		Impedance 100 Ohms (Diff)	
Layer	Trace Width (mils)	Trace Width (mils)	Trace Spacing (mils)	Trace Width (mils)	Trace Spacing (mils)
Top Layer					

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
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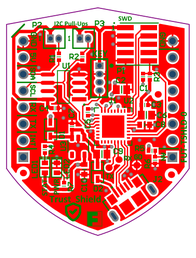
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



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5. FINISH - HASL RoHS [X] HASL [ ] Immersion Silver [ ] Immersion Tin [ ] ENIG [ ]
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6. SOLDER MASK - APPLY SOLDER MASK AS PER SPECIFIED IPC-SM-840 ON PCB OVER BARE COPPER
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7. SILKSCREEN - LPI - APPLY EPOXY BASED INK
   - TOP/BOTTOM [X] TOP ONLY [ ] BOTTOM ONLY [ ] NONE [ ]
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8. IMPEDANCE CONTROL - NO [X] YES [ ] SEE TABLE FOR DETAIL

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Designed by: M. Bernier	Drawn by: M. Bernier
Checked by: M. Bernier	Approved by: M. Bernier

Future Electronics – System Design Center NA
237 Hymus Blvd
Pointe-Claire, Quebec, Canada
H9R 5C7

Project #	TrustFlex_Shield_RevO	
Title:	TrustFlex Shield board	
Size: B	DWG NO: FEN-524534-PCB-RO	REV: O
Date: 2/24/2020	Sheet 1 of 1	

Layers		Bottom Layer

Impedance Requirements

	Impedance 50 Ohms	Impedance 90 Ohms (Diff)		Impedance 100 Ohms (Diff)	
Layer	Trace Width (mils)	Trace Width (mils)	Trace Spacing (mils)	Trace Width (mils)	Trace Spacing (mils)
Bottom Layer					

Layer	Name	Material	Thickness	Constant	Board Layer Stack
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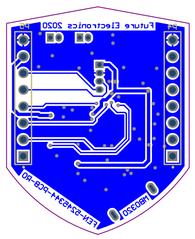

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6. SOLDER MASK - APPLY SOLDER MASK AS PER SPECIFIED IPC-SM-840 ON PCB OVER BARE COPPER
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7. SILKSCREEN - LPI - APPLY EPOXY BASED INK
   - TOP/BOTTOM ☒ TOP ONLY ☐ BOTTOM ONLY ☐ NONE ☐
   - WHITE ☒ BLACK ☐ Other ☐ _____

8. IMPEDANCE CONTROL - NO ☒ YES ☐ SEE TABLE FOR DETAIL

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Project #	TrustFlex_Shield_RevO	
Title:	TrustFlex Shield board	
Size: B	DWG NO: FEN-524534-PCB-R0	REV: 0
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